

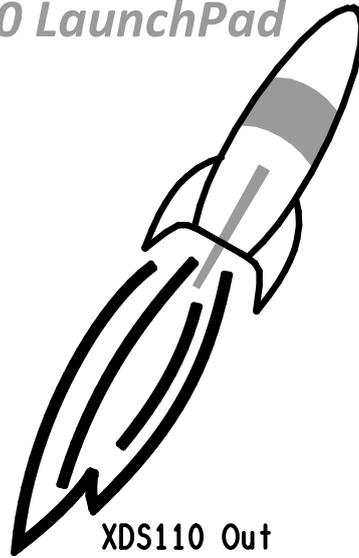
Reset



TEXAS
INSTRUMENTS

CC1350 LaunchPad

Rev: 1.1



XDS110 Out

VSENSE

XDS110
Power
Extern.
Pwr.

BTN-1
DIO13



RXD<< TXD>> RESET TMS TCK TDI TDO SWO

CC1350 In

BTN-2
DIO14

J1 1 21 J3

3V3

5V

DIO23



DIO2

DIO25

DIO3

DIO26

DIO22

DIO27

DIO24

DIO28

DIO10

DIO29

DIO21

DIO30

DIO4

DIO0

DIO5

DIO1

10 30

J4 40 20 J2

DIO7



BP LP

DIO6

DIO12

DIO20

DIO11

DIO19

NC

DIO18

LPRST

BPRST

DIO9

TMS

DIO8

TCK

DIO13

DIO16

DIO14

DIO17

DIO15

31 11



5V

Red: DIO6
Green: DIO7



3V3

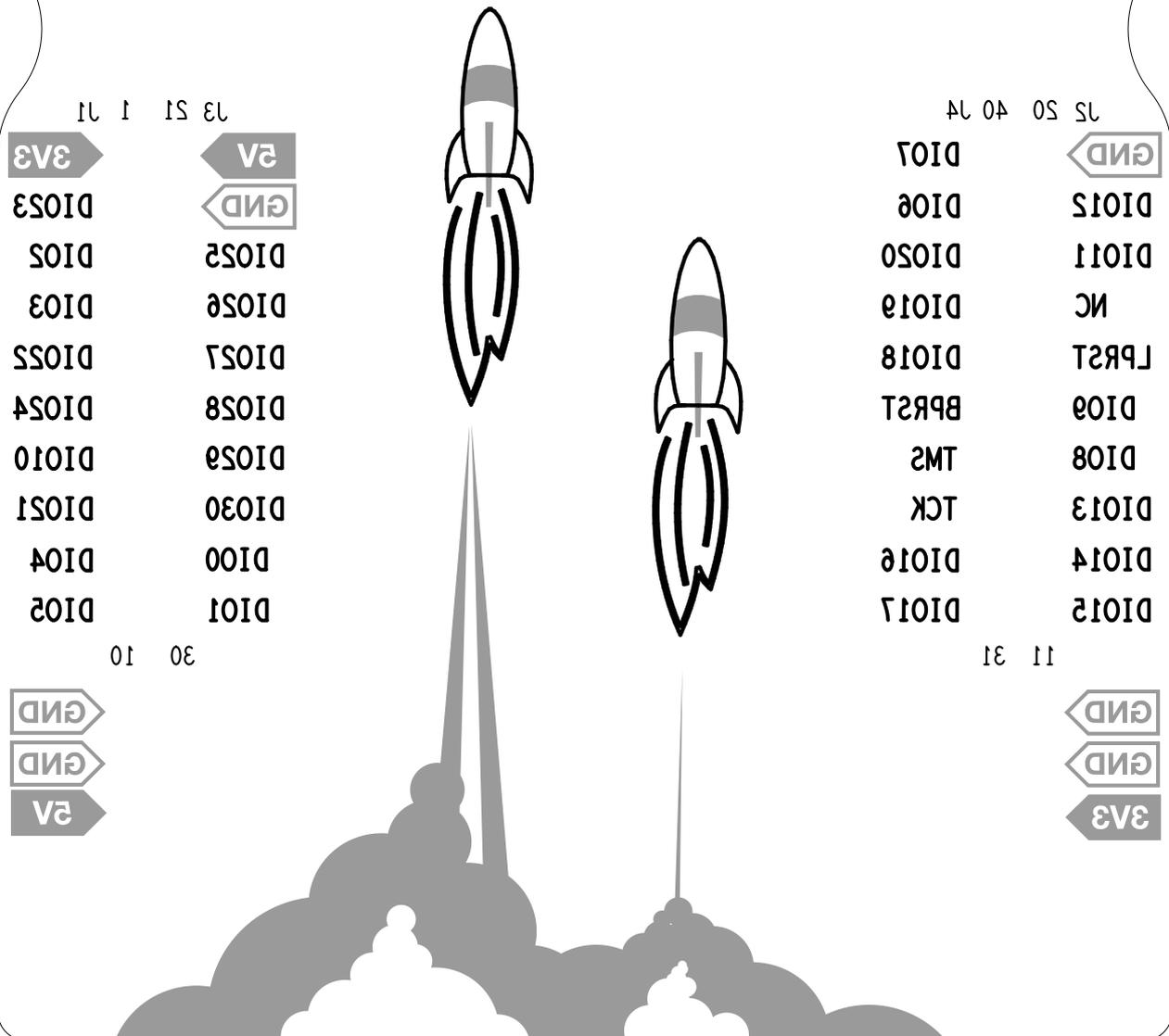
Mount for:
CC-ANTENNA-DK

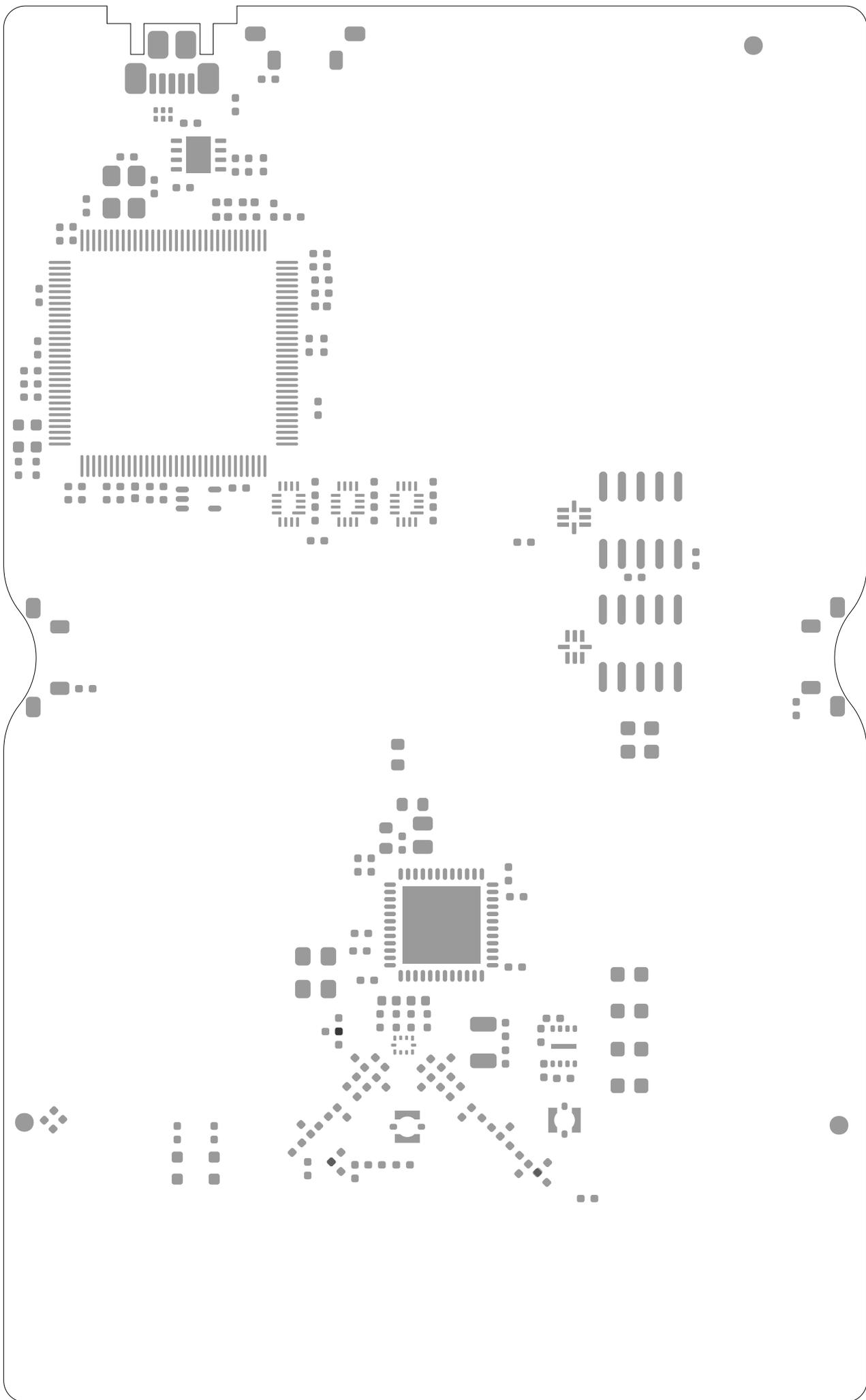


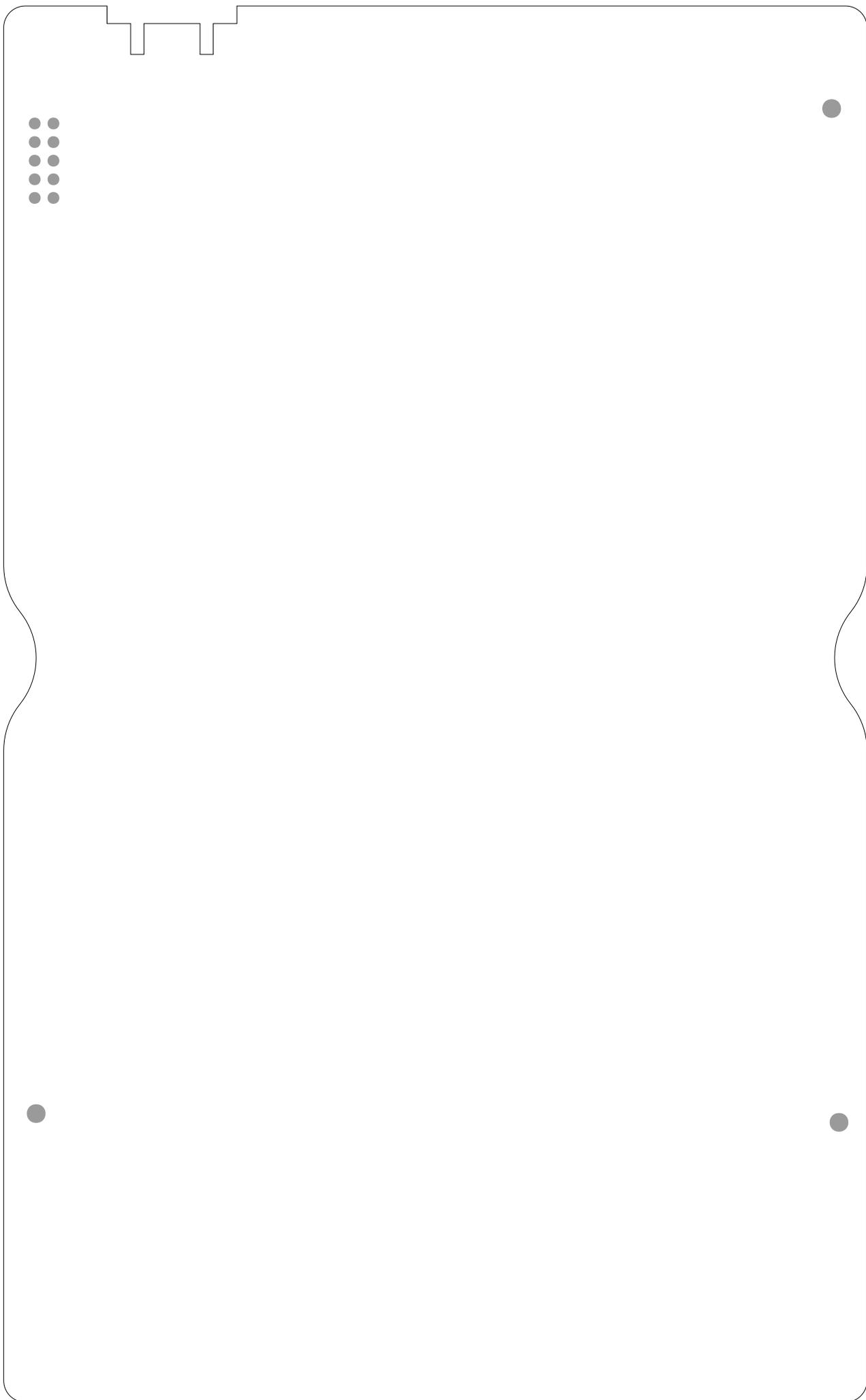
89

CC1350 LaunchPad
<<LAUNCHL-CC1350
www.ti.com/launchpad

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